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***Wide Range Input TPS40051  
Converter Delivers 5 Volts at 2 Amps***

***User's Guide***

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# Wide Range Input TPS40051 Converter Delivers 5 Volts at 2 Amps

System Power

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## 1 Introduction

The TPS40051EVM-002 wide range input dc-to-dc converter utilizes the TPS40051 synchronous rectifier controller to step down a 10-V to 40-V input to 5 V. The output current is 3 A with an input of 10 V and should be linearly derated to 2 A at  $V_{IN} = 40$  V. The TPS40051 is utilized because it offers a variety of user programmable functions such as operating frequency, soft start, voltage feed-forward, high-side current limit, and external loop compensation. This controller provides a regulated 10-V gate drive supply which feeds the bootstrap charging circuit for the high-side N-channel MOSFET along with a driver for the low-side synchronous rectifier MOSFET. The device operation is specified in the TPS40051 datasheet<sup>[1]</sup>.

## 2 Features

- Operates from an input source varying from 10 V<sub>DC</sub> to 40 V<sub>DC</sub>
- Output current 3 A with  $V_{IN} = 10$  V, 2 A with  $V_{IN} = 40$  V
- Low cost high voltage conversion



## 4 Component selection

### 4.1 TPS40051 Device Selection

The TPS4005X family of parts offers a range of output current configurations including source only (TPS40050), source/sink (TPS40051), or source/sink with  $V_{OUT}$  prebias (TPS40053). In this converter the TPS40051 with source/sink capability is selected. This serves to maintain continuous inductor ripple current all the way to zero load to improve the small signal loop response by preventing the inductor current from transitioning to the discontinuous current mode.

The TPS4005X family is packaged in TI's PWP PowerPAD™ thermally enhanced package which should be soldered to the PCB using standard solder flow techniques. In the PowerPAD™, a thermally conductive epoxy is utilized to attach the integrated circuit die to the leadframe die pad, which is exposed on the bottom of the completed package. The PWP PowerPAD™ package has a  $\theta_{JC} = 2^{\circ}\text{C}/\text{W}$  which helps keep the junction temperature rise relatively low even with the power dissipation inherent in the onboard MOSFET drivers. This power loss is proportional to switching frequency, drive voltage, and the gate charge needed to enhance the N-channel MOSFETs. Effective heat removal allows the use of ultra small packaging while maintaining high component reliability.

The Texas Instrument Technical Brief, PowerPAD™ Thermally Enhanced Package Application Report[2] should be consulted for more information on the PowerPAD™ package.

### 4.2 Frequency of Operation

The clock oscillator frequency for the TPS40051 is programmed with a single resistor from RT (pin 2) to signal ground. The following equation (1) from the datasheet allows selection of RT in kΩ for a given switching frequency in kHz.

$$R_T = R_2 = \frac{1}{f_{SW} \times 17.82 \times 10^{-6}} - 23 \text{ k}\Omega \quad (1)$$

For 300-kHz RT is selected to be 165 kΩ.

In addition to programming the operating frequency, the PWM ramp time must be programmed via the resistor  $R_{KFF}$  up to  $V_{IN}$ . Also, the selection of  $R_{KFF}$  programs the  $V_{IN}$  voltage at which the circuit starts operation. This helps keep the circuit from starting at low voltages, which can lead to current flow larger than desired. Now,  $R_{KFF}$  is programmed using equation (2)

$$R_{KFF} = R_5 = (V_{IN(\min)} - 3.5) \times (58.14 \times R_T + 1340 \text{ k}\Omega) \quad (2)$$

where  $V_{IN(\min)}$  should be the minimum startup input voltage, and  $R_T$  is in kΩ. Note that internal tolerances have been incorporated into this equation, so the actual  $V_{IN(\min)}$  of the input voltage should be used here. For 300-kHz  $R_{KFF}$  is selected to be 71.5 kΩ.

### 4.3 UVLO circuitry

The user programmable UVLO built into the TPS4005X provides hysteresis for transients shorter than a total count of seven cycles. If the input voltage to the converter can be slowly rising around the minimum  $V_{IN}$  range, external hysteresis can be incorporated to prevent multiple on/off cycles during startup or shutdown. These on/off cycles are a result of line impedance external to the EVM causing  $V_{IN}$  to the module to drop when under load, causing the programmable UVLO threshold to be crossed repetitively.

In this converter, C16 and D2 are added to form a peak detector from the lower gate drive which is only active when the converter is operating. This provides a bias source to deliver hysteresis current from the peak detector voltage through R12 to the lower KFF voltage of 3.5 V, enabling one to alter the programmable UVLO shutdown point. The bias is not present during startup, so the circuit starts as expected from the  $R_{KFF}$  calculation.

In this application, R12 is selected to provide a hysteresis current of 20%  $I_{KFF}$  and can be calculated from

$$R_{HYS} = R12 = \frac{R_{KFF} \times (V_{PD} - 3.5)}{0.2 \times (V_{IN(min)} - 3.5)} \quad (3)$$

where  $V_{PD}$  is the voltage on the peak detector, and  $V_{IN(min)}$  is the desired start voltage used in the determination of  $R_{KFF}$ . In our typical case,  $V_{PD} = 8$  V, and R12 is found to be 247 k $\Omega$ , and a standard value of 243 k $\Omega$  is selected. Testing shows the startup voltage to be 9.2 V, and the shutdown voltage to be 8.5 V.

### 4.4 Inductance value

The output inductor value for a buck converter can be selected from equation (4).

$$L = \frac{V_{OUT}}{f \times I_{RIPPLE}} \left( 1 - \frac{V_{OUT}}{V_{IN(min)}} \right) \quad (4)$$

in which  $I_{RIPPLE}$  is usually chosen to be in the range of 10% to 40% of  $I_{OUT}$ . With  $I_{RIPPLE} = 20\%$  of  $I_{OUT(max)}$  there is a ripple current of 0.6 A, and the inductance value is found to be 24  $\mu$ H for a maximum  $V_{IN}$  of 40 V. In a wide range  $V_{IN}$  design the inductor value selection involves a lot of compromise. This design specifically targets the higher voltage range of operation attainable with the TPS40051 controller, so a standard value 22- $\mu$ H inductor is selected. With a 22- $\mu$ H inductor, the ripple current with  $V_{IN} = 10$  V is 0.38 A, and the ripple with  $V_{IN} = 40$  V is 0.66 A. Using the larger inductor at lower voltages helps to reduce the number of output capacitors required to meet the output noise specification, as discussed in a later section. If the input range was constrained to a lower voltage range such as 10 V to 16 V a smaller inductor would be selected.

A ferrite drum core with a surface mount carrier provides a low-cost solution inductors in this inductance/current range. Inductors rated 22  $\mu$ H are available in a couple of sizes, with the larger versions generally rated to carry higher saturation current, which is the current for 30% inductor value rolloff. In this example an inductor with a  $\frac{1}{2}$  inch diameter drum core is selected because the saturation current is rated 7.6 A. The next physically smaller inductor has a saturation rating of 3.7 A, and does not allow sufficient margin for the tolerances in the current limit circuitry.

## 4.5 Input capacitor selection

The bulk input capacitor selection is based on several factors such as size, cost, and meeting voltage ripple requirements. There are multiple configurations of various capacitor technologies that can function in the application. In this example the goal is to achieve reduced overall cost in the solution provided.

The RMS current required by the power stage will be supplied by both the onboard capacitance and the input source, with the relative impedances determining the magnitude of RMS current carried by each component. In typical applications, this reference design would be fed from an upstream dc-to-dc converter with its own bulk output capacitance, so the impedance presented to this converter could be rather low and less onboard capacitance would be required. On the other hand, if conductors used to bring input power to this converter have high series impedance then the onboard capacitors would be forced to carry more of the RMS ripple current, and capacitors with higher current rating would be needed.

The maximum RMS current required for the buck power stage can be estimated as shown in equation (5),

$$I \approx I_{\text{OUT}} \times \sqrt{D} = I_{\text{OUT}} \times \sqrt{\frac{V_{\text{OUT}}}{V_{\text{IN}}}} = 3 \times \sqrt{\frac{5}{10}} = 2.1 \text{ A} \quad (5)$$

It is also important to consider a minimum capacitance value which would limit the voltage ripple to a specified value if all the current is supplied by the onboard capacitor. For a typical ripple voltage of 150 mV the minimum capacitance is calculated in equation (6) as:

$$C = \frac{I \times \Delta t}{\Delta V} = \frac{I \times V_O}{\Delta V \times V_{\text{IN}} \times F_S} = \frac{3.3 \text{ A} \times 5 \text{ V}}{0.5 \text{ V} \times 10 \text{ V} \times 300 \text{ kHz}} = 11 \mu\text{F} \quad (6)$$

Initially, this design was fitted with a ceramic capacitor rated 10  $\mu\text{F}$ , 50 V because some of the current would also be supplied from the input source, limiting the voltage ripple to a value below the estimate. However, when testing with a fast switch-on time there was voltage overshoot of 15 V to 20 V above the input source voltage. This is a result of parasitic inductance in series with the input source interacting with the low-ESR ceramic capacitor. To eliminate this issue the capacitor was changed to a 1.5- $\mu\text{F}$ , 50-V ceramic capacitor in parallel with a 100- $\mu\text{F}$  aluminum electrolytic capacitor.

The 1.5- $\mu\text{F}$  ceramic capacitor C6 is positioned as a power bypass component located close to the MOSFET packages to keep the high frequency current flow in a small, tight loop. The 100- $\mu\text{F}$  capacitor C11 has an ESR of 0.35  $\Omega$ , max which serves to dampen out the transient overshoot.



## 4.6 Output capacitor selection

Selection of the output capacitor is based on many application variables, including function, cost, size, and availability. The minimum allowable output capacitance is determined by the amount of inductor ripple current and the allowable output ripple, as given in equation (7)

$$C_{\text{OUT(min)}} = \frac{I_{\text{RIPPLE}}}{8 \times f \times V_{\text{RIPPLE}}} = \frac{0.66 \text{ A}}{8 \times 300 \text{ kHz} \times 15 \text{ mV}} = 18 \mu\text{F} \quad (7)$$

In this design,  $C_{\text{OUT(min)}}$  is 18- $\mu\text{F}$  with  $V_{\text{RIPPLE}} = 15 \text{ mV}$ . However, this only affects the capacitive component of the ripple voltage, and the final value of capacitance is generally influenced by ESR and transient considerations. To limit the voltage to 15 mV, the capacitor ESR should be less than equation (8),

$$R_C \leq \frac{V_{\text{RIPPLE}}}{I_{\text{RIPPLE}}} = \frac{15 \text{ mV}}{0.66 \text{ A}} = 0.023 \text{ m}\Omega \quad (8)$$

An additional consideration in the selection of the output inductor and capacitance value can be derived from examining the transient voltage overshoot which can be initiated with a load step from full load to no load. By equating the inductive energy with the capacitive energy the equation (9) can be derived:

$$C_O = \frac{L \times I^2}{V^2} = \frac{L \times (I_{\text{OH}}^2 - I_{\text{OL}}^2)}{(V_f^2 - V_i^2)} = \frac{22 \mu\text{H} \times (3 \text{ A})^2}{(5.1 \text{ V})^2 - (5.0 \text{ V})^2} = 196 \mu\text{F} \quad (9)$$

where  $I_{\text{OH}} = \text{full load}$ ,  $I_{\text{OL}} = \text{no load}$ ,  $V_f = \text{allowed transient voltage rise}$ , and  $V_i = \text{initial voltage}$ . In this 3-A design the capacitance required for limiting the transient is significantly larger than the capacitance required to keep the ripple acceptably low. A single 330- $\mu\text{F}$  POSCAP capacitor C13 is installed in parallel with a 1- $\mu\text{F}$  ceramic capacitor.

## 4.7 MOSFET selection

This wide range design required selection of a MOSFET capable of withstanding the maximum input voltage of 40 V, and still capable of carrying the maximum load current of 3 A without overheating. This low cost design utilizes a single SO-8 package which contains two MOSFETs, each rated for 55 V, and an  $R_{\text{DS(on)}}$  of 55m $\Omega$ .

In a synchronous buck converter the fast-rising switch node voltage drives current through the drain-gate and gate-source capacitance of the synchronous rectifier. This can raise the gate of the lower MOSFET to threshold level even though the gate driver is attempting to hold the gate low.<sup>[3]</sup> C17 is added to the gate of Q1:B to increase the capacitance ratio between the gate-source and drain-gate, reducing the voltage which appears on the lower MOSFET gate.

## 4.8 Short circuit protection

The TPS40051 implements short circuit protection by comparing the voltage across the topside MOSFET while it is ON to a voltage developed across  $R_{LIM}$  due to an internal current source of 10  $\mu\text{A}$  inside pin 16. Both of these voltages are negative with respect to  $V_{IN}$ . From the datasheet equation,  $R_{LIM}$  is defined as:

$$R_{LIM} = R9 = \frac{I_{OC} \times R_{DS(on)}}{1.12 \times I_{SINK}} + \frac{V_{OS}}{I_{SINK}} \Omega \quad (10)$$

Here,  $I_{OC}$  is the overcurrent set point equal to the dc output current plus one half the inductor ripple current,  $V_{OS}$  is the overcurrent comparator offset, and  $I_{SINK}$  is the current into the  $I_{LIM}$  pin 16. Using worst case tolerances the value of  $R_{LIM}$  should be maximized to ensure that the converter can deliver full rated current under all conditions. Looking at worst case conditions,  $R_{LIM} = R9$  is found to be:

$$R_{LIM} = \frac{(3 \text{ A} + 0.3 \text{ A}) \times (55 \text{ m}\Omega \times 1.4)}{1.12 \times 8.65 \mu\text{A}} + \frac{-23 \text{ mV}}{8.65 \mu\text{A}} = 23.5 \text{ k}\Omega \quad (11)$$

The standard value of 23.5  $\text{k}\Omega$  was selected. This ensures that we can deliver a minimum of 3 A before current limit is activated. There is also a small capacitor, C8, placed in parallel with R9 to filter the signal.

## 4.9 Snubber component selection

The junction of Q1, Q2, and L1 rises fast enough to contribute to  $dV/dT$  induced voltage on the gate of Q1:B. A snubber consisting of C12 and R10 is added to slow down the rise time of the switch node.

## 4.10 Compensation components

The TPS40051 uses voltage mode control in conjunction with a high frequency error amplifier. The power circuit L/C double pole corner frequency  $f_c$  is situated at 1.8 kHz. The feedback compensation network is implemented to provide two zeroes and three poles. The first pole is placed at the origin to improve dc regulation.

The two zeros are placed near 1.96 kHz,

$$f_{z1} = \frac{1}{2 \times \pi \times R_4 \times C_4} \quad (12)$$

and

$$f_{z2} = \frac{1}{2 \times \pi \times (R_6 + R_7) \times C_5} \quad (13)$$

The second pole is placed at 66 kHz,

$$f_{p1} = \frac{1}{2 \times \pi \times R_4 \left( \frac{C_3 \times C_4}{C_3 + C_4} \right)} \quad (14)$$

and the third pole is placed at 159 kHz, which is near one-half of the switching frequency.

$$f_{p2} = \frac{1}{2 \times \pi \times R_7 \times C_5} \quad (15)$$

## 5 Test Setup

Figure 2 illustrates the basic test setup needed to evaluate the TPS40051EVM-001.

### 5.1 DC Input Source

The input voltage source should be capable of supplying from 10 V<sub>DC</sub> to 40 V<sub>DC</sub> and rated for at least 3 A of current. For best results the input leads should be made with a wire of 22 gauge or larger wire.

### 5.2 Output Load

The output load can be either an electronic load or a resistive load configured to draw between 0 A and 3 A. The output leads should be made with a wire of 20 AWG or larger diameter wire. A voltmeter should be connected to TP6 and TP7 to monitor the output voltage on the PCB.

### 5.3 Oscilloscope Probe Test Jacks

An oscilloscope probe test jack (TP8) has been included to allow monitoring the output voltage ripple.

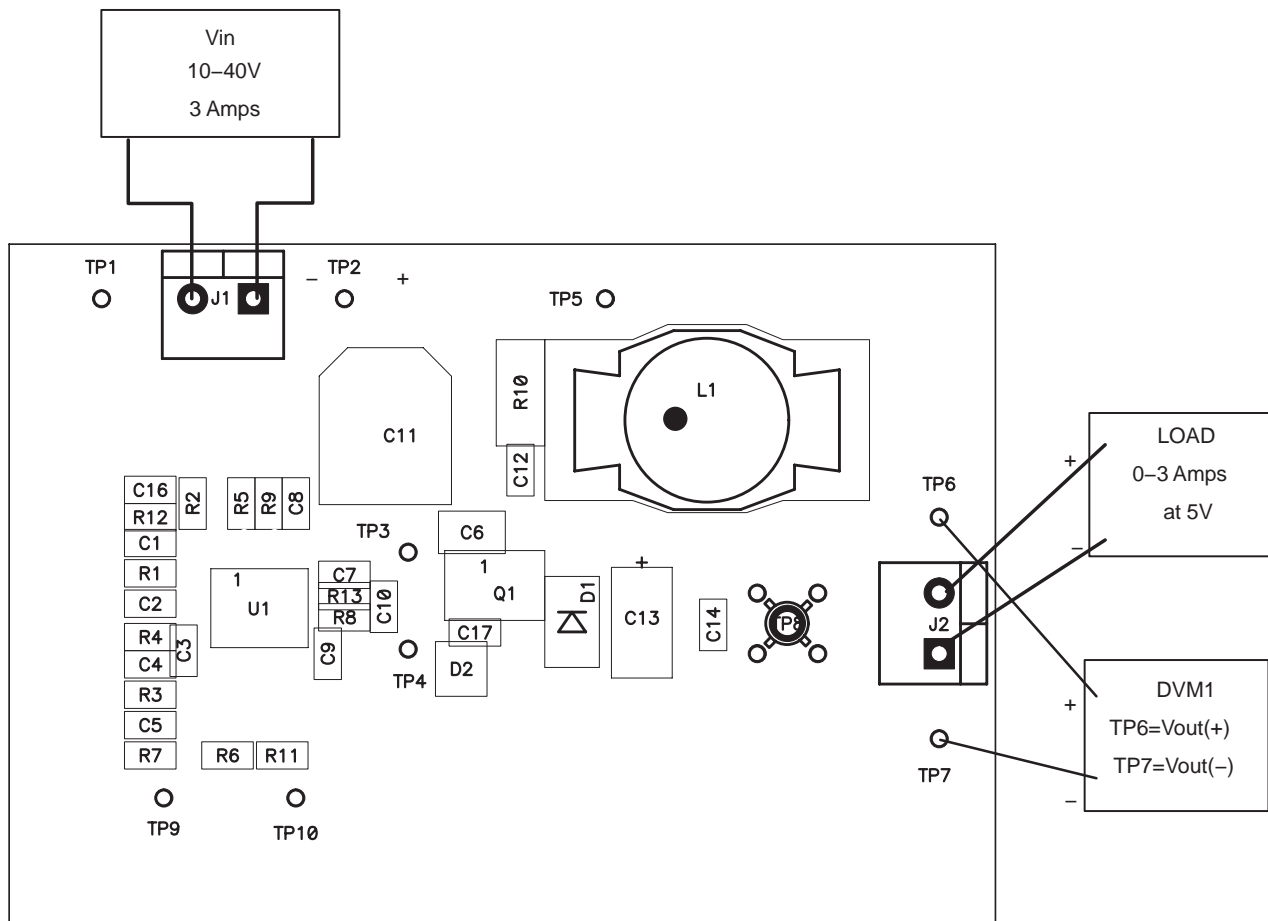


Figure 2. Test Setup

## 6 Test Results/Performance Data

### 6.1 Efficiency

Figure 3 shows the efficiency as the load is varied from 0.5 A to over 3 A.

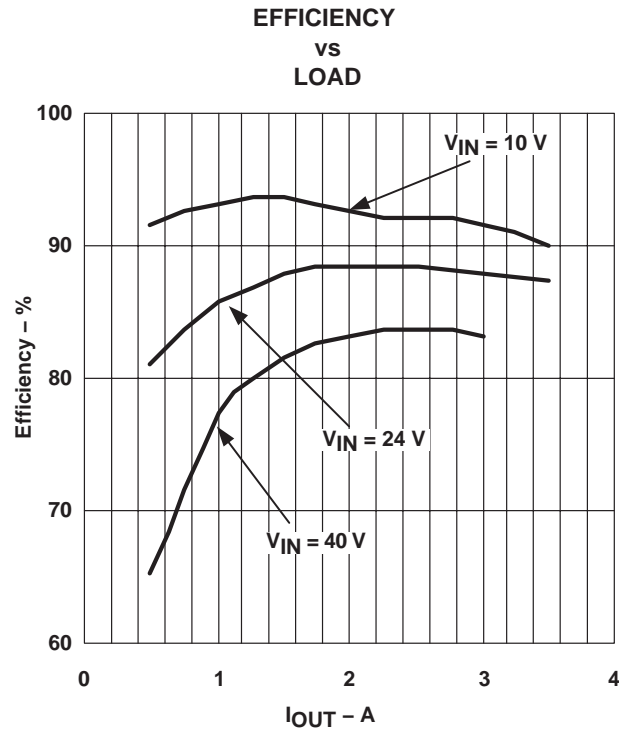
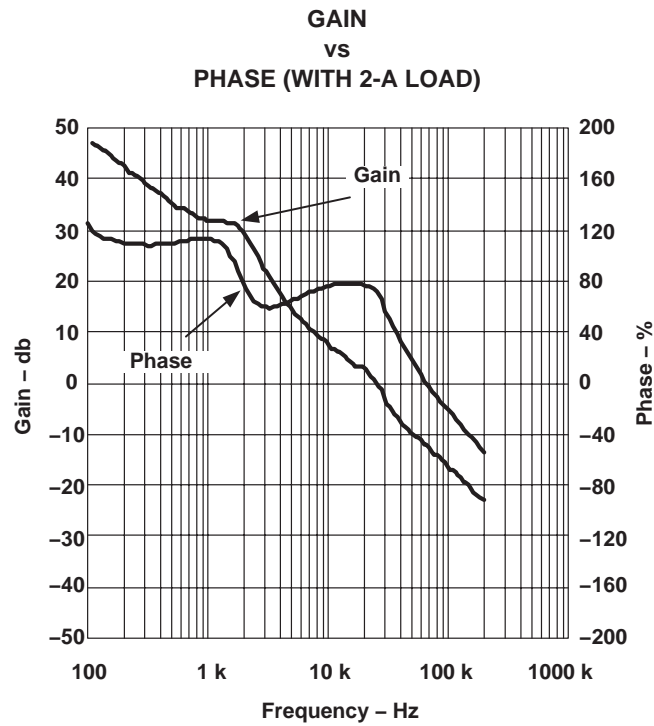


Figure 3

## 6.2 Closed loop performance

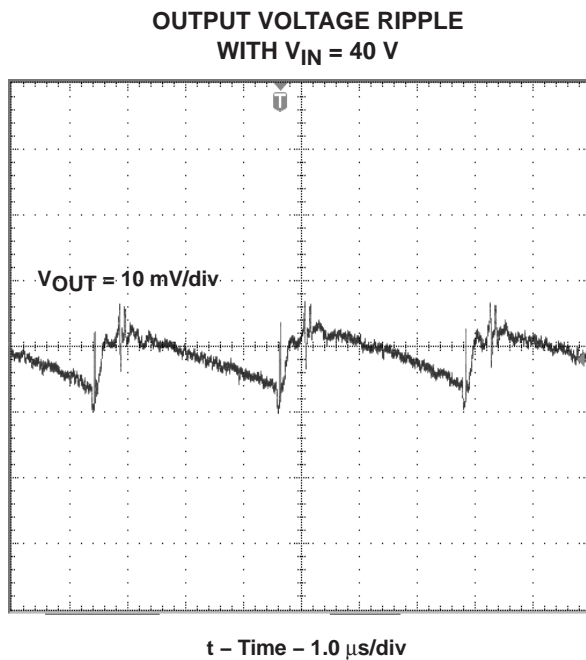
The TPS40051 uses voltage mode control with feed-forward in conjunction with a high frequency error amplifier to implement closed loop control.



**Figure 4**

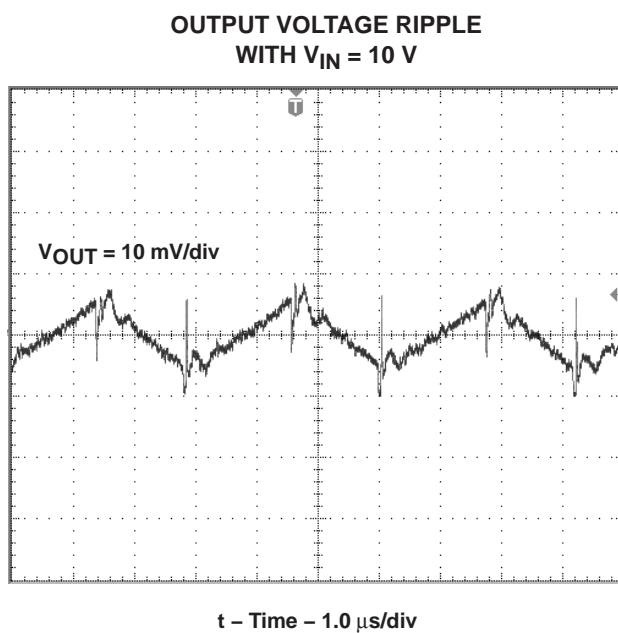
### 6.3 Output Ripple and Noise

Figure 5 shows typical output noise with  $V_{IN} = 40\text{ V}$ ,  $I_{OUT} = 2\text{ A}$ .



**Figure 5**

Figure 6 shows typical output noise with  $V_{IN} = 10\text{ V}$ ,  $I_{OUT} = 3\text{ A}$ .



**Figure 6**

## 6.4 Transient Response

The transient response is shown in Figure 7 as the load is stepped from 0.5 A to 2.5 A with  $V_{IN} = 24$  V. With the 2-A load step the output deviation is approximately 30 mV.

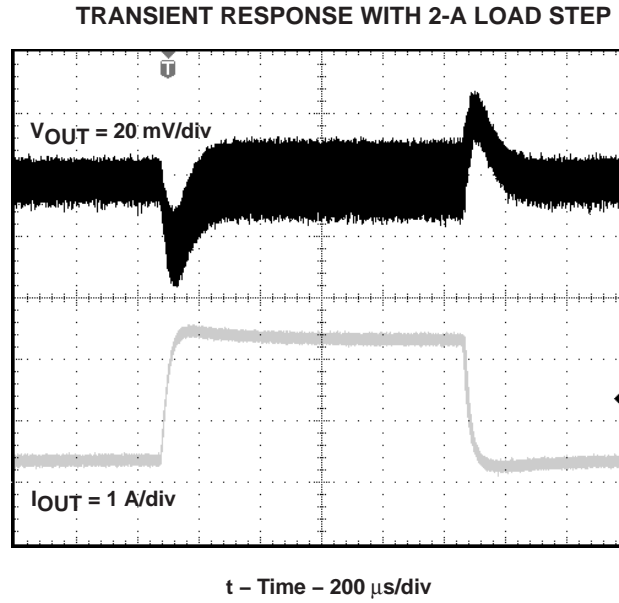


Figure 7

## 7 EVM Assembly Drawing and PCB Layout

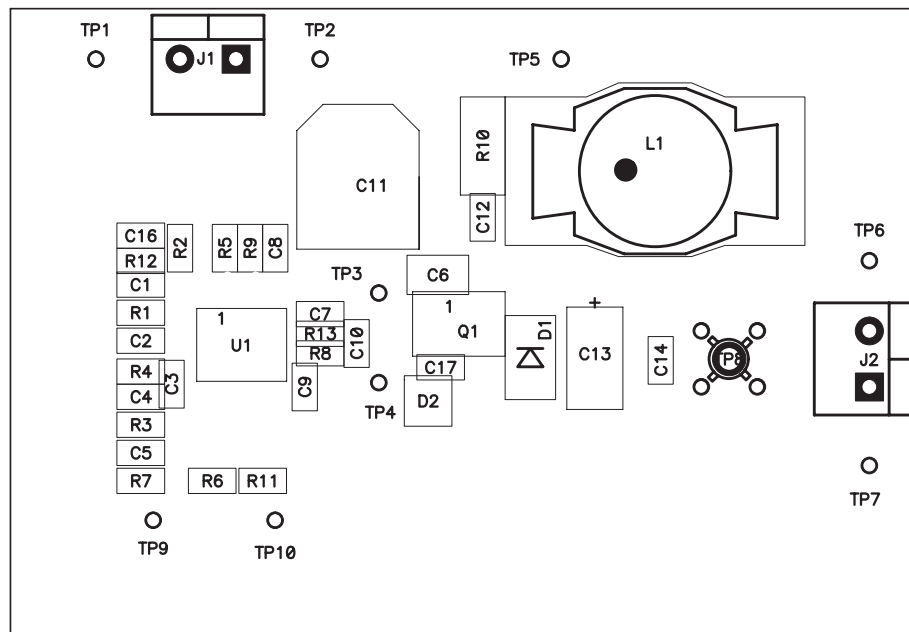
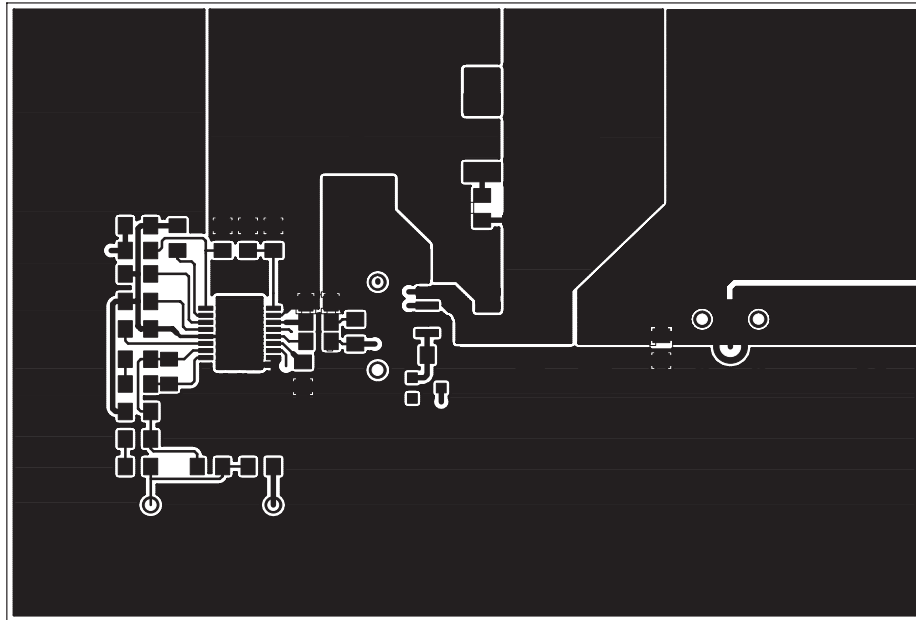
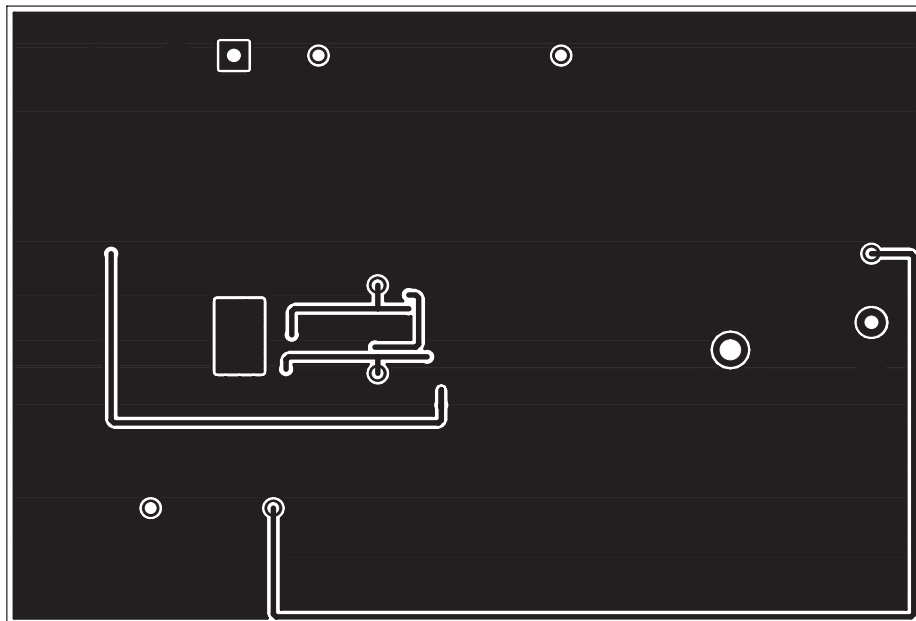


Figure 8. Top Side Component Assembly



**Figure 9. Top Layer Copper**



**Figure 10. Bottom Layer Copper**



## 8 List of Materials

The following table lists the TPS40051EVM–002 components corresponding to the schematic shown in Figure 1.

**Table 1. TPS40051EVM–002 (SLUP195) List of Materials**

| REFERENCE DESIGNATOR               | QTY | DESCRIPTION  | MFR           | PART NUMBER     |
|------------------------------------|-----|--|---------------|-----------------|
| C1, C7, C10                        | 3   | Capacitor, ceramic, 0.1 $\mu$ F, 25 V, X7R, 10%, 805                 | Vishay        | VJ0805Y104KXXAT |
| C11                                | 1   | Capacitor, aluminum, 100 $\mu$ F, 63 V, 20%, 0.457 x 0.406           | Panasonic     | EEVFK1J101P     |
| C13                                | 1   | Capacitor, POSCAP, 330 $\mu$ F, 6.3 V, 10 m $\Omega$ , 20%, 7343 (D) | Sanyo         | 6TPD330M        |
| C9, C14                            | 2   | Capacitor, ceramic, 1.0 $\mu$ F, 16 V, X5R, 20%, 805                 | TDK           | C2012X5R1C105KT |
| C16                                | 1   | Capacitor, ceramic, 470 pF, 50 V, X5R, 20%, 805                      | Vishay        | VJ0805Y471KXAAT |
| C2, C12, C17                       | 3   | Capacitor, ceramic, 2.2 nF, 50 V, X7R, 10%, 805                      | Vishay        | VJ0805Y222KXAAT |
| C3                                 | 1   | Capacitor, ceramic, 82 pF, 50 V, NPO, 5%, 805                        | Panasonic     | VJ0805A820KXAAT |
| C4                                 | 1   | Capacitor, ceramic, 2.7 nF, 50 V, X7R, 10%, 805                      | Vishay        | VJ0805Y272KXAAT |
| C5                                 | 1   | Capacitor, ceramic, 10 nF, 50 V, X7R, 10%, 805                       | Vishay        | VJ0805Y103KXAAT |
| C6                                 | 1   | Capacitor, ceramic, 1.5 $\mu$ F, 50 V, X7R, 10%, 1210                | TDK           | C3225X7R1H155KT |
| C8                                 | 1   | Capacitor, ceramic, 100 pF, 50 V, X7R, 10%, 805                      | Vishay        | VJ0805A101KXAAT |
| D1                                 | 1   | Diode, schottky, 1 A, 60 V, SMB                                      | IR            | 10BQ060         |
| D2                                 | 1   | Diode, switching, 10 mA, 85 V, 350 mW, SOT23                         | Vishay–Liteon | BAS16           |
| J1, J2                             | 2   | Terminal block, 2 pin, 15 A, 5.1 mm, 0.40 x 0.35                     | OST           | ED1609          |
| L1                                 | 1   | Inductor, SMT, 22 $\mu$ H, 4.5 A, 34 m $\Omega$ , 0.87x0.59          | Coiltronics   | UP4B–220        |
| Q1                                 | 1   | MOSFET, dual N–channel, 60 V, 3.8 A, 55 m $\Omega$ , SO8             | Siliconix     | Si4946EY        |
| R1                                 | 1   | Resistor, chip, 1 k $\Omega$ , 1/10 W, 1%, 805                       | Std           | Std             |
| R10                                | 1   | Resistor, chip, 4.7 $\Omega$ , 1 W, 5%, 2512                         | Std           | Std             |
| R11                                | 1   | Resistor, chip, 20 $\Omega$ , 1/10 W, 1%, 805                        | Std           | Std             |
| R12                                | 1   | Resistor, chip, 243 k $\Omega$ , 1/10 W, 1%, 805                     | Std           | Std             |
| R13                                | 1   | Resistor, chip, 8.2 $\Omega$ , 1/10 W, 5%, 805                       | Std           | Std             |
| R2                                 | 1   | Resistor, chip, 165 k $\Omega$ , 1/10 W, 1%, 805                     | Std           | Std             |
| R3                                 | 1   | Resistor, chip, 1.27 k $\Omega$ , 1/10 W, 1%, 805                    | Std           | Std             |
| R4                                 | 1   | Resistor, chip, 30.1 k $\Omega$ , 1/10 W, 1%, 805                    | Std           | Std             |
| R5                                 | 1   | Resistor, chip, 71.5 k $\Omega$ , 1/10 W, 1%, 805                    | Std           | Std             |
| R6                                 | 1   | Resistor, chip, 7.87 k $\Omega$ , 1/10 W, 1%, 805                    | Std           | Std             |
| R7                                 | 1   | Resistor, chip, 100 $\Omega$ , 1/10 W, 1%, 805                       | Std           | Std             |
| R8                                 | 1   | Resistor, chip, 3.3 $\Omega$ , 1/10 W, 5%, 805                       | Std           | Std             |
| R9                                 | 1   | Resistor, chip, 23.5 k $\Omega$ , 1/10 W, 1%, 805                    | Std           | Std             |
| TP1, TP7                           | 2   | Jack, test point, black  | Farnell       | 240–333         |
| TP2, TP3, TP4, TP5, TP6, TP9, TP10 | 7   | Jack, test point, red  | Farnell       | 240–345         |
| TP8                                | 1   | Adaptor, 3.5-mm probe clip ( or 131–5031–00), 0.2                    | Tektronix     | 131–4244–00     |
| U1                                 | 1   | IC, Wide Input Synchronuos Buck Controller, PWP16                    | TI            | TPS40051PWP     |
| --                                 | 1   | PCB, 3.25 In x 2.25 In x .031 In                                     | Any           | SLVP236         |

## 9 References

1. Data Sheet, *TPS40051 Wide-Input Synchronous Buck Controller*, Texas Instruments Literature No. SLUS540.
2. Technical Brief, *PowerPAD™ Thermally Enhanced Package*, Texas Instruments Literature No. SLMA002
3. Seminar Topic, *A Design and Application Guide for High Speed MOSFET Gate Drive Circuits*, Texas Instruments Literature No. SLUP169

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